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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/912,558	07/26/2001	Ronald A. Weimer	M4065.0319/P319-A	5990
	90 99/28/2004		EXAM	INER
DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP			KIELIN, ERIK J	
2101 L STREET WASHINGTON	I NW I, DC 20037-1526		,	PAPER NUMBER
			2813	
			DATE MAILED: 09/28/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	
Advisory Action	09/912,558	WEIMER ET AL.	
Advisory Action	Examiner	Art Unit	
	Erik Kielin	2813	
The MAILING DATE of this communication appe	ears on the cover sheet with the c	correspondence add	ress
THE REPLY FILED 21 September 2004 FAILS TO PLA Therefore, further action by the applicant is required to a final rejection under 37 CFR 1.113 may only be either: (condition for allowance; (2) a timely filed Notice of Appe Examination (RCE) in compliance with 37 CFR 1.114.	void abandonment of this application (1) a timely filed amendment whi	cation. A proper re	ply to a cation in
PERIOD FOR RE	EPLY [check either a) or b)]		
a) The period for reply expiresmonths from the mailing of the period for reply expires on: (1) the mailing date of this Advance, will the statutory period for reply expire later the ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS 706.07(f). Extensions of time may be obtained under 37 CFR 1.136(a). The data have been filed is the date for purposes of determining the period of extensions of the shortened at the contract of the shortened states.	visory Action, or (2) the date set forth in the INITY AND ARTHS FROM THE MAILING DATE OF THE	f the final rejection. E FINAL REJECTION. 136(a) and the appropriate fee. The appropriate ex the final Office action; or	See MPEP e extension fee tension fee under (2) as set forth in
(b) above, if checked. Any reply received by the Office later than three more earned patent term adjustment. See 37 CFR 1.704(b).	onths after the mailing date of the final rejo	ection, even if timely filed,	, may reduce any
 A Notice of Appeal was filed on Appellant' 37 CFR 1.192(a), or any extension thereof (37 CF 			
2. ☐ The proposed amendment(s) will not be entered be	ecause:		
(a) X they raise new issues that would require furth	er consideration and/or search ((see NOTE below);	
(b) ☐ they raise the issue of new matter (see Note	below);		
(c) they are not deemed to place the application issues for appeal; and/or	in better form for appeal by mat	terially reducing or	simplifying the
(d) they present additional claims without cance	ling a corresponding number of	finally rejected clai	ms.
NOTE: See Continuation Sheet.			
3.☐ Applicant's reply has overcome the following reject	ction(s):		
 Newly proposed or amended claim(s) would canceling the non-allowable claim(s). 	I be allowable if submitted in a s	separate, timely file	d amendment
5.☐ The a)☐ affidavit, b)☐ exhibit, or c)☐ request for application in condition for allowance because:		sidered but does No	OT place the
6. The affidavit or exhibit will NOT be considered be raised by the Examiner in the final rejection.	cause it is not directed SOLELY	to issues which we	ere newly
7. For purposes of Appeal, the proposed amendmen explanation of how the new or amended claims w			and an
The status of the claim(s) is (or will be) as follows	:		
Claim(s) allowed: <u>none</u> .			
Claim(s) objected to: <u>none</u> .			
Claim(s) rejected: <u>13,14,16,17 and 42</u> .			
Claim(s) withdrawn from consideration: none.			
8. The drawing correction filed on is a) ap	proved or b) disapproved by	the Examiner.	
9. Note the attached Information Disclosure Stateme			

Erik Kielin Primary Examiner

10. Other: ____

Continuation of 2. NOTE: At least the new limitation of subjecting the dielectric film to a densifying treatment to stabilize said film by heating the semicondudor substrate prior to the wet oxidation is a new issue.